Title (en)

PULSED MODE DEPOSITION FOR LOW RATE FILM DEPOSITION

Title (de)

BESCHICHTUNG IM GEPULSTEN BETRIEB FÜR FILMBESCHICHTUNG MIT NIEDRIGER RATE

Title (fr)

DEPOT EN MODE PULSE DE FILMS A FAIBLE DEBIT

Publication

EP 0968318 A1 20000105 (EN)

Application

EP 98958522 A 19981110

Priority

- US 9823968 W 19981110
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Abstract (en)

[origin: WO9927151A1] A pulsed mode sputtering method and system for sputtering a material from a target onto a substrate in a sputtering deposition process to create thin films. The thin films are created by generating pulsed power from a power supply operated in pulsed mode. The power supply can be either a DC or RF power supply. The pulsed power is applied at full load during the power on portion and at a significantly reduced power (e.g., at 5 % of the full load power) during the power off portion. The pulsed power is applied to the target to sputter the target material onto the substrate at a reduced deposition rate to create a thin film on the substrate. Uniform films having thicknesses of less than 50 angstroms can be created using this pulsed mode deposition technique.

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C23C 14/34

IPC 8 full level

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Citation (search report)

See references of WO 9927151A1

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